

Fab Notes Unless Otherwise Specified:

1. Workmanship shall conform to IPC Class 2 Specifications.
2. PCB: 4 Layers 0.047"(1.2mm) or closest thickness to 0.047"(1.2mm)+/- standard tolerance
3. Hole sizes after plating are defined in the Drill Guide: *.drl
4. Other Drill information can be found in the *.gd1,2,x and *.gg1,2,x Gerber Files
5. Minimums: Trace/space = 8mil / 5mil Min Via Hole = 10mil Min Via Pad = 22mil
6. **NO PCB Vendor Logo, date code, or other markings on PCB. On Rails ONLY!!**
7. Finish = Lead Free Solder
8. Silkscreen = WHITE
9. Solder mask to be BLACK and shall conform to the requirements specified. Soldermask both sides.
10. Gerber File Extensions:
 - .GTL = Top Layer
 - .G1 = Internal Layer, L2
 - .G2 = Internal Layer, L3
 - .GBL = Bottom Layer
 - .GTO = Top Silk
 - .GTP = Top Pastemask
 - .GTS = Top Soldermask
 - .GBS = Bottom Soldermask
 - .GBP = Bottom Pastemask
 - .GBO = Bottom Silkscreen(if present)
 - .GM1 = Board Outline/Dimensions
 - .GM2 = Fab Notes/Dimensions
 - .GM8 = Bottom Designators(if present)
 - .GM9 = Top Designators
 - .GM15 = Component Outline
 - .GM16 = Border/Title
 - .GD1 = Drill Drawing L1-L4
 - .GG1 = Drill Guide L1-L4

Tab-Route Details:

Place into 10-20 piece tab-routed arrays.
 Create suitable spacing between PCB's
 via tab-routed array with multiple mouse-bites.
 Individual PCB: 99.1 x 63.5mm
 Add 0.5" rails on sides of Array
 Add Fiducials and Tooling Holes on Rails
 as needed for proper PCB assembly.
 Any Vendor ID's MUST be on Rails ONLY!!

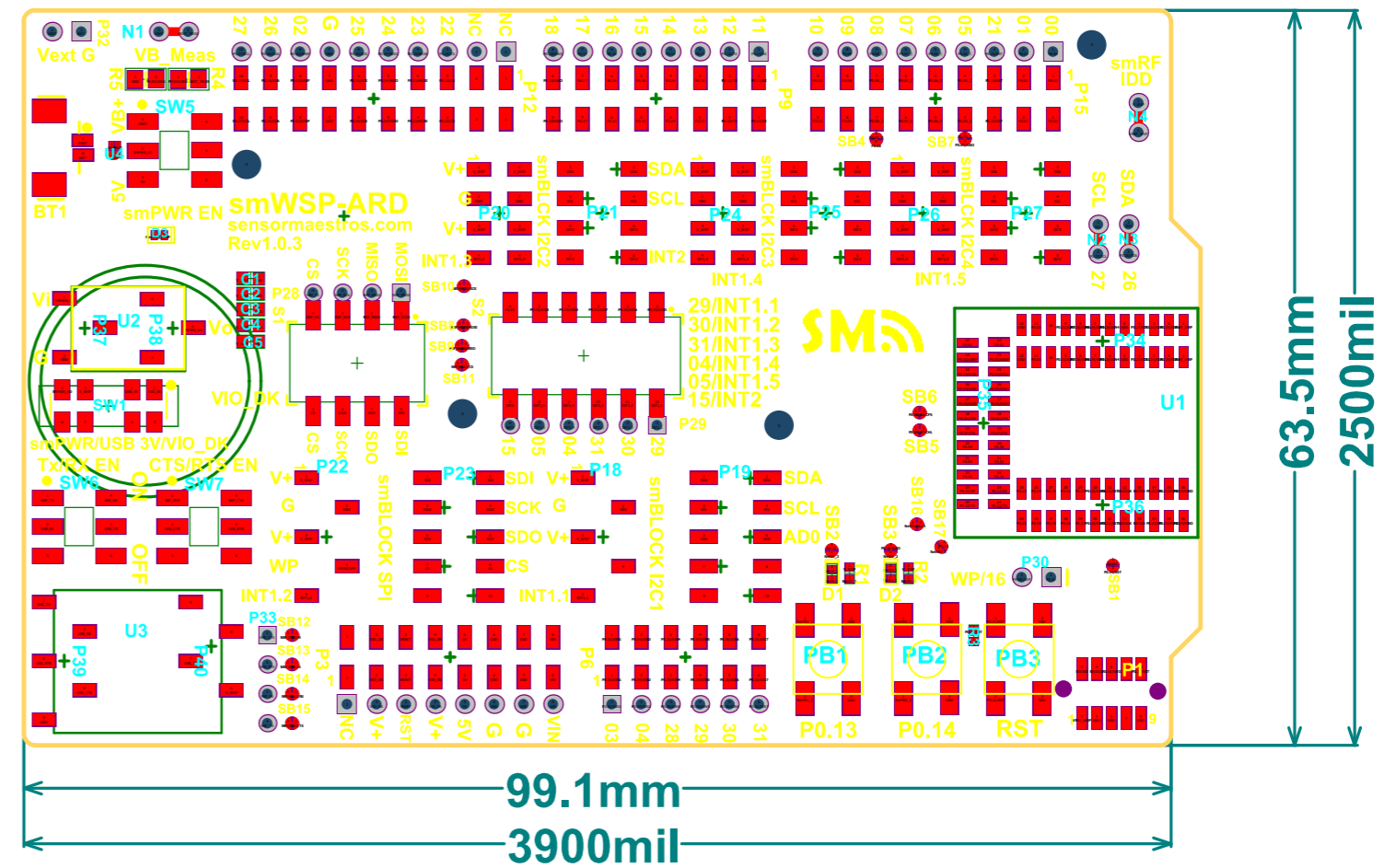
Assembly Details:

Bottom Components NEED to be assembled FIRST!!
 Top components to be assembled LAST!!
 Assemble with standard reflow temperatures.

Layer Stack Up Detail for: smWSEP-ARD.PcbDoc

Layer
Name

- Top Layer
- L2
- L3
- Bottom Layer



Sensor Maestros www.sensormaestros.com Born at High Altitude in Denver Colorado	ENGINEER:	TITLE:	<h1>smWSP-ARD</h1>	
	PCB DESIGNER:			
	DATE:	4/27/2017	PART NO.:	REV: 1.0.3
	FILE NAME:	smWSEP-ARD.PcbDoc	DWG NO.:	SCALE:

